

江苏浩都频率科技有限公司

JIANGSU HD-CRYSTAL TECHNOLOGY CO., LTD

Specifications For Product

TYPE: Quartz Crystal Oscillator

SPEC: QMEMS2016/24.000M/1.8V/±30PPM

P/N : 8T024000101

VER: A/1

R&D APPR.SIGNATURED			DEPT.
ISSUE	CHECK	APPROVAL	新華科· 新華科· 新華科· 新華科· 新華科· 新華科· 新華科· 新華科·
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Specification Revision Record Sheet

Rev.	Revise page	Revise Contents	Date	Ref. No.	Reviser
A/0	N/A	Initial released	2018/3/30	N/A	吴佳斌
A/1	N/A	P/N revision	2020/1/1	N/A	吴佳斌

Product Descipion

8T024000101

- 1. Scope:
- 1.1 This specification applies to the RoHS crystal oscillator with a frequency of 24.000MHz which will be used in electronic equipment.



- 2. Construction:
- 2.1 Oscillators series: QMEMS2016 8T series
- 2.2 Package: SMD 2.0×1.6
- 3. Electrical Characteristics

3.1	Nominal Frequency:	24.000MHz
3.2	Frequency Stability:	±30ppm
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(incl. 25°C tolerance, tolerance over operating temperature range, input voltage change, load change, 1 year aging)

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3.3	Aging:	±3ppm/year
3.4	Operating Temperature Range:	-40 to + 85°C
3.5	Storage Temperature Range:	-55 to + 125°C
3.6	Input Voltage (V _{DD}):	+1.8Vdc±10%
3.7	Input Current (I _{DD}):	20mA max
3.8	Output Waveform:	CMOS
3.9	Output Symmetry:	50±10%
3.10	Rise/Fall Time:	8ns max
3.11	Output Voltage V _{OL} :	10%VDD
	V _{OH} :	90%VDD

3.12 Output Load: 15pF

3.13 Output State Control: Enable/disable

3.14 Start-up Time: 10ms max3.15 Standby current: 10μA max

3.16 Phase Jitter (rms): 1ps rms max 12kHz to 20MHz max

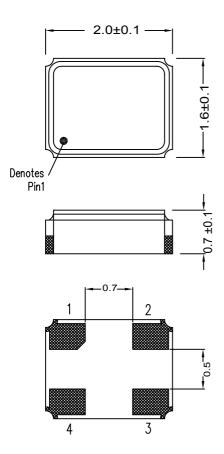
3.17 Oscillation mode: Fundmental

3.18 Others: Not recommended for safety applications

Reliability Specification

NO.	ITEM	SPECIFICATION	TEST METHOD
4.1	Temperature Cycle (GB/T 2423.22-2002, Method Nb)	Frequency change after test≤± 5ppm.	10 cycles from -55°C to 125°C. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.2	Low Temperature Storage (GB/T 2423.1-2001, Method Aa)	Frequency change after test≤± 5ppm.	Spending 72 hrs at -55°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.3	High Temperature Storage (GB/T 2423.2-2001, Method Ba)	Frequency change after test≤± 5ppm.	Spending 72 hrs at 125°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.4	Humidity (GB/T 2423.3- 2006, Method Cab)	Frequency change after test≤± 5ppm.	Spending 96 hrs at 40 °C ± 3 °C, with 90± 3% R.H. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.5	Vibration (GB/T 2423.10- 1995, Method Fc)	Frequency change after test≤± 5ppm.	Apply 0.75mm vibration at sweep frequency $10\sim500$ Hz, for 2h. 10 cycles in each direction of 3 axis. Measurement taken after 1 hour.
4.6	Shock (GB/T 2423.5-1995, Method Ea)	Frequency change after test≤± 5ppm. No visible damages.	Peak 1000m/s2, normal width 6ms half sine wave form, 3.7m/s, 3 perpendicular axis of samples, 3 cycles / direction, total 18 cycles. Measurement taken after 1 hour.
4.7	Drop (GB/T 2423.8-1995, Method Ed)	Frequency change after test≤± 5ppm. No visible damages.	Free drop to the wooden plate from 1.0 m heights for 3 times.
4.8	Solderability (GB/T 2423.28-2005, Method Tc)	Terminals shall be covered more then 95% with solder.	In 245 \pm 5°C solder bath for 2 \pm 0.5 seconds. There is no need to do functioned test. 8-12X magnifier.
4.9	Terminal Strength (JIS-C-6429 Method 1 & 2)	No visible damage	Mount on a glass-epoxy board (100x50x1.6mm), then bend to 2mm displacement (velocity 1mm/sec) and keep for 5 seconds. or pulling force 0.5 kg for at least 60 seconds.
4.10	Resistance to Soldering Heat (GB/T 2423.28-2005, Test Tb Method 1B)	Frequency change after test≤± 5ppm.	Passed through the re-flow oven under the following condition. Preheat to 150°C±5°C for 60 to 120sec,and peak 265°C±5°C for 10s±3sec.Measurement taken after DUT being left at room temperature for at 24±2 hours.
4.11	OTHERS		

Package Outline Dimensions



PIN CONNECTION

P/N	Features
1	Enable/Disable*
2	GND
3	Output
4	VDD

Packing Specification

